



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	$V_{(BR)DSS}$ $R_{DS(on) max}$ I_{D} $T_{A} = +2$	
-40V	11mΩ @ V _{GS} = -10V	-10.1A
-40 V	15mΩ @ V _{GS} = -4.5V	-8.8A

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) test in production
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

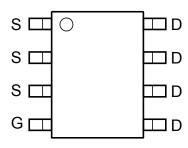
- DC-DC Converters
- Power management functions
- Analog Switch

Mechanical Data

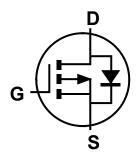
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)



Top View



Top View Internal Schematic



Equivalent circuit

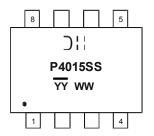
Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
DMP4015SSS-13	Standard	SO-8	2,500/Tape & Reel

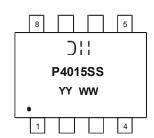
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Chengdu A/T Site



Shanghai A/T Site

⊃¦¦ = Manufacturer's Marking
P4015SS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 13 = 2013)
WW = Week (01 - 53)

YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	-40	V		
Gate-Source Voltage		_	V_{GSS}	±25	V
Continuous Drain Current (Note 5) V _{GS} = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-9.1 -7.2	Α
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-7.8 -6.2	Α
Continuous Drain Current (Note 6) V _{GS} = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-10.1 -8	Α
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-8.8 -7	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I_{DM}	-100	Α		
Avalanche Current (Note 7)	I _{AS}	-22	Α		
Avalanche Energy (Note 7)	Eas	242	mJ		

Thermal Characteristics

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P _D	1.45	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	88	°C/W
Total Power Dissipation (Note 6)	P _D	1.82	W
Thermal Resistance, Junction to Ambient (Note 6)	R _{0JA}	70	°C/W
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta Jc}$	7.6	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

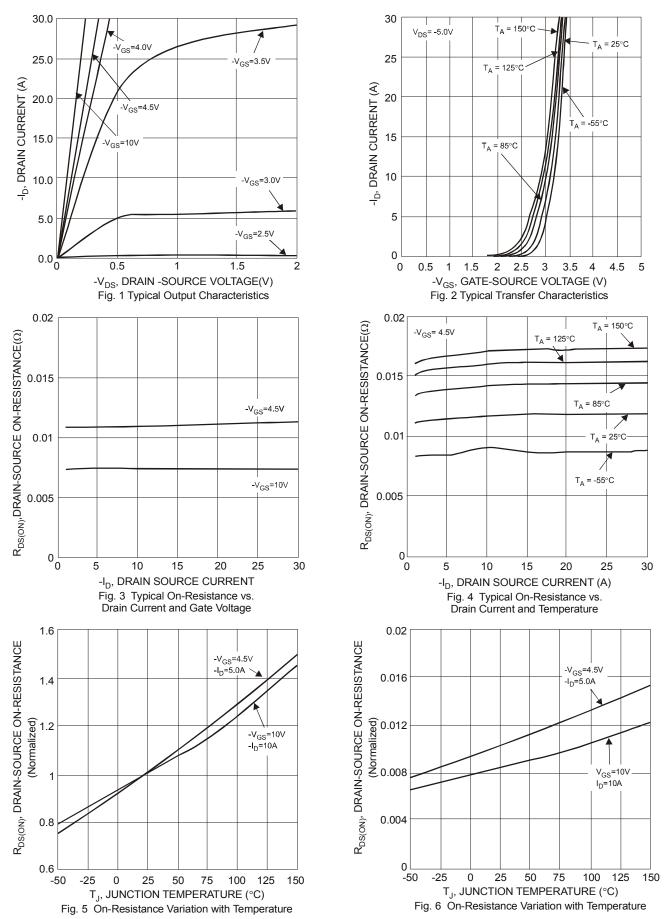
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)	Symbol	IVIIII	тур	IVIAA	Oilit	Test Condition	
Drain-Source Breakdown Voltage	BV _{DSS}	-40	_		V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	-1	μA	V _{DS} = -40V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	V _{GS} = ±25V, V _{DS} = 0V	
ON CHARACTERISTICS (Note 8)		l.		ı	l.	1 22	
Gate Threshold Voltage	V _{GS(th)}	-1.5	-2	-2.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Ctatic Dunin Course On Besistance		_	7	11	0	V _{GS} = -10V, I _D = -9.8A	
Static Drain-Source On-Resistance	R _{DS} (ON)	_	9	15	mΩ	$V_{GS} = -4.5V$, $I_D = -9.8A$	
Forward Transfer Admittance	Y _{fs}	_	26	_	S	V _{DS} = -20V, I _D = -9.8A	
Diode Forward Voltage (Note 5)	V _{SD}	_	-0.7	-1	V	V _{GS} = 0V, I _S = -1A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	_	4234	_		.,	
Output Capacitance	Coss	_	1036	_	pF	$V_{DS} = -20V, V_{GS} = 0V$ f = 1MHz	
Reverse Transfer Capacitance	C _{rss}	_	526	_		I - IIVITZ	
Gate Resistance	Rg	_	7.77	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	_	47.5	_			
Gate-Source Charge	Q _{gs}	_	14.2	_	nC	$V_{DS} = -20V, V_{GS} = -5V$	
Gate-Drain Charge	Q_{gd}	_	13.5	_		$I_D = -9.8A$	
Turn-On Delay Time	t _{D(on)}	_	13.2	_			
Turn-On Rise Time	tr	_	10	_		$V_{GS} = -10V, V_{DD} = -20V, R_G = 6\Omega,$	
Turn-Off Delay Time	t _{D(off)}	_	302.7	_	ns	$I_D = -1A$, $R_L = 20\Omega$	
Turn-Off Fall Time	t _f	_	137.9	_			

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate 7 .UIS in production with L = 1mH, T_J = +25°C
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to production testing.









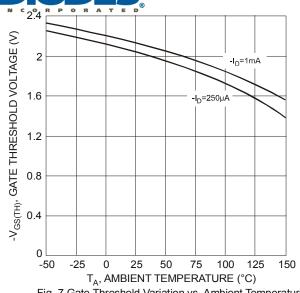
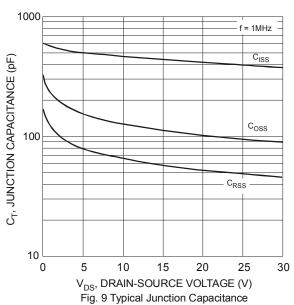
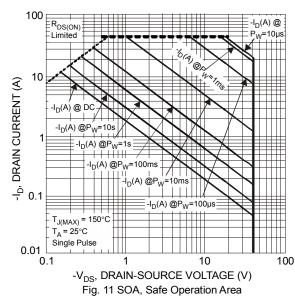
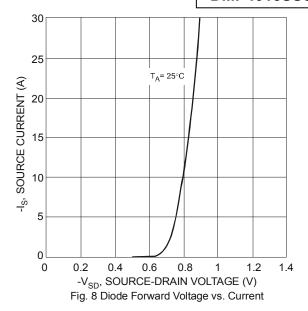
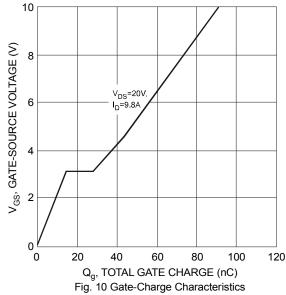


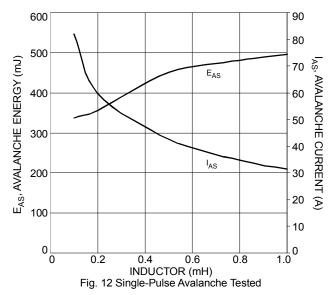
Fig. 7 Gate Threshold Variation vs. Ambient Temperature



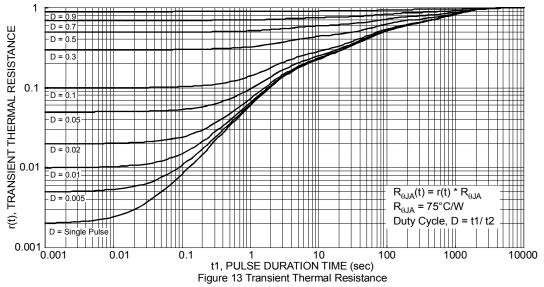






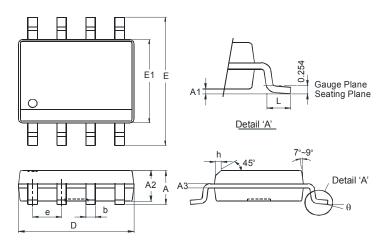






Package Outline Dimensions

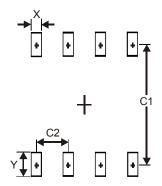
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SO-8					
Dim	Min	Max			
Α	-	1.75			
A 1	0.10	0.20			
A2	1.30	1.50			
A3	0.15	0.25			
b	0.3	0.5			
D	4.85	4.95			
Е	5.90	6.10			
E1	3.85	3.95			
е	1.27 Typ				
h	- 0.35				
L	0.62 0				
θ	0°	8°			
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.60
Υ	1.55
C1	5.4
C2	1.27



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